

# Ziren Wang

## List of Publications by Year in descending order

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17  
papers

50  
citations

2258059

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1872680

6  
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times ranked

24  
citing authors

| #  | ARTICLE  | IF  | CITATIONS |
|----|--|-----|-----------|
| 1  | The Impact of Gold Plating Process for Bonding Pads on Interconnection Quality. IEEE Transactions on Device and Materials Reliability, 2022, , 1-1.  | 2.0 | 0         |
| 2  | Modeling and Analysis of Signal Integrity of Ball Grid Array Packages With Failed Ground Solder Balls. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 306-315.         | 2.5 | 7         |
| 3  | Investigation of impedance compensation in radio frequency circuits with bonding wire. International Journal of RF and Microwave Computer-Aided Engineering, 2022, 32, .                                   | 1.2 | 3         |
| 4  | The Impact of Connector Degradation on Signal Transmission in Humid Environment. , 2021, , .   |     | 0         |
| 5  | Intelligent Detection Methods of Electrical Connection Faults in RF Circuits. Applied Sciences (Switzerland), 2021, 11, 9973.  | 2.5 | 2         |
| 6  | The Impact of Connection Failure of Bonding Wire on Signal Transmission in Radio Frequency Circuits. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1729-1737.         | 2.5 | 9         |
| 7  | Symmetry degradation of differential circuits induced by uneven gold plating of high-speed connectors in extreme environment. Microwave and Optical Technology Letters, 2020, 62, 3716-3726.               | 1.4 | 0         |
| 8  | Investigations on the Effect of Electrical Contact Degradation on High Speed Wide-Band Signal Integrity. Chinese Journal of Electronics, 2020, 29, 525-532.  | 1.5 | 2         |
| 9  | Impact of receptacle degradation and loose connection on signal integrity and electrical performance repeatability. IET Circuits, Devices and Systems, 2020, 14, 1012-1017.                                | 1.4 | 1         |
| 10 | Impact of Impedance Change Caused by Bonding Wire Connection on Signal Transmission. , 2020, , .   |     | 0         |
| 11 | Impact of the Ball Grid Array Connection Failures on Signal Integrity. , 2020, , .   |     | 3         |
| 12 | Modeling and Analysis of Signal Integrity of High-Speed Interconnected Channel With Degraded Contact Surface. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 2227-2236. | 2.5 | 8         |
| 13 | High-Frequency Behavior Analysis and Modeling of Silver Plated Printed Circuit Board with Electrochemical Migration. Journal of Electronic Materials, 2019, 48, 8039-8046.                                 | 2.2 | 3         |
| 14 | Investigation of the improvement of signal integrity in electrical circuits with degraded contacts using differential transmission. IET Circuits, Devices and Systems, 2019, 13, 303-308.                  | 1.4 | 1         |
| 15 | Study on the Effects of RF Coaxial Connector Degradation on Signal Integrity using S Parameters. , 2019, , .   |     | 3         |
| 16 | The Impact of Electrical Contact Degradation on Differential Signal Transmission of High Speed Channel. , 2018, , .  |     | 4         |
| 17 | Impedance Compensation of the Welding Area of the RF Connector and Microstrip Line. , 2018, , .  |     | 4         |